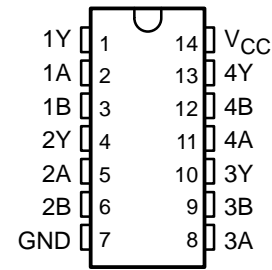


# CD54AC02, CD74AC02 QUADRUPLE 2-INPUT POSITIVE-NOR GATES

SCHS304C – JANUARY 2001 – REVISED JUNE 2002

- AC Types Feature 1.5-V to 5.5-V Operation and Balanced Noise Immunity at 30% of the Supply Voltage
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Balanced Propagation Delays
- $\pm 24$ -mA Output Drive Current  
– Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

CD54AC02 . . . F PACKAGE  
CD74AC02 . . . E OR M PACKAGE  
(TOP VIEW)



## description

The 'AC02 devices contain four independent 2-input NOR gates that perform the Boolean function  $Y = \overline{A} \cdot \overline{B}$  or  $Y = \overline{A + B}$  in positive logic.

## ORDERING INFORMATION

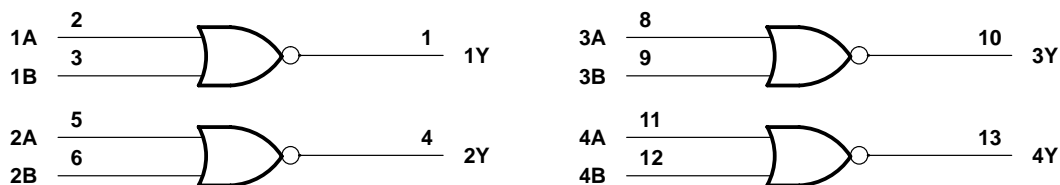
T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	PDIP – E	Tube	CD74AC02E	CD74AC02E
	SOIC – M	Tube	CD74AC02M	AC02M
		Tape and reel	CD74AC02M96	
	CDIP – F	Tube	CD54AC02F3A	CD54AC02F3A

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## FUNCTION TABLE (each gate)

INPUTS		OUTPUT
A	B	Y
H	X	L
X	H	L
L	L	H

## logic diagram (positive logic)



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# CD54AC02, CD74AC02 QUADRUPLE 2-INPUT POSITIVE-NOR GATES

SCHS304C – JANUARY 2001 – REVISED JUNE 2002

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$	-0.5 V to 6 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	$\pm 50$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	$\pm 50$ mA
Continuous current through $V_{CC}$ or GND	$\pm 100$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package	80°C/W
M package	86°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 3)

		$T_A = 25^\circ\text{C}$		$-40^\circ\text{C TO } 85^\circ\text{C}$		$-55^\circ\text{C TO } 125^\circ\text{C}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	1.5	5.5	1.5	5.5	1.5	5.5	V
$V_{IH}$	High-level input voltage	$V_{CC} = 1.5\text{ V}$		1.2		1.2		V
		$V_{CC} = 3\text{ V}$		2.1		2.1		
		$V_{CC} = 5.5\text{ V}$		3.85		3.85		
$V_{IL}$	Low-level input voltage	$V_{CC} = 1.5\text{ V}$			0.3		0.3	V
		$V_{CC} = 3\text{ V}$			0.9		0.9	
		$V_{CC} = 5.5\text{ V}$			1.65		1.65	
$V_I$	Input voltage	0	$V_{CC}$	0	$V_{CC}$	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$		-24		-24		mA
$I_{OL}$	Low-level output current	$V_{CC} = 4.5\text{ V to } 5.5\text{ V}$		24		24		mA
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 1.5\text{ V to } 3\text{ V}$		50		50		ns/V
		$V_{CC} = 3.6\text{ V to } 5.5\text{ V}$		20		20		

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



# CD54AC02, CD74AC02 QUADRUPLE 2-INPUT POSITIVE-NOR GATES

SCHS304C – JANUARY 2001 – REVISED JUNE 2002

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C		–40°C TO 85°C		–55°C TO 125°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = –50 μA	1.5 V	1.4	1.4	1.4			V	
			3 V	2.9	2.9	2.9				
			4.5 V	4.4	4.4	4.4				
		I <sub>OH</sub> = –4 mA	3 V	2.58	2.48	2.4				
		I <sub>OH</sub> = –24 mA	4.5 V	3.94	3.8	3.7				
		I <sub>OH</sub> = –50 mA†	5.5 V			3.85				
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 50 μA	1.5 V	0.1	0.1	0.1		V		
			3 V	0.1	0.1	0.1				
			4.5 V	0.1	0.1	0.1				
		I <sub>OL</sub> = 12 mA	3 V	0.36	0.44	0.5				
		I <sub>OL</sub> = 24 mA	4.5 V	0.36	0.44	0.5				
		I <sub>OL</sub> = 50 mA†	5.5 V			1.65				
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5 V		±0.1	±1	±1	μA			
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	5.5 V		4	40	80	μA			
C <sub>i</sub>				10	10	10	pF			

† Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

**switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 1.5 V, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–40°C TO 85°C		–55°C TO 125°C		UNIT
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y		131		144	ns
t <sub>PHL</sub>			131	144			

**switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ± 0.3 V, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–40°C TO 85°C		–55°C TO 125°C		UNIT
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	4.1	14.6	4	16.1	ns
t <sub>PHL</sub>			4.1	14.6	4	16.1	



# CD54AC02, CD74AC02 QUADRUPLE 2-INPUT POSITIVE-NOR GATES

SCHS304C – JANUARY 2001 – REVISED JUNE 2002

switching characteristics over recommended operating free-air temperature range,  
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ ,  $C_L = 50\text{ pF}$  (unless otherwise noted) (see Figure 1)

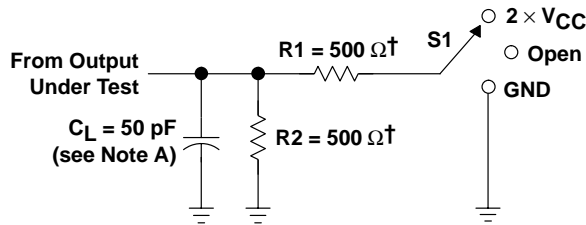
PARAMETER	FROM (INPUT)	TO (OUTPUT)	-40°C TO 85°C		-55°C TO 125°C		UNIT
			MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	Y	3	10.4	2.9	11.5	ns
t <sub>PHL</sub>			3	10.4	2.9	11.5	

operating characteristics,  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	55	pF



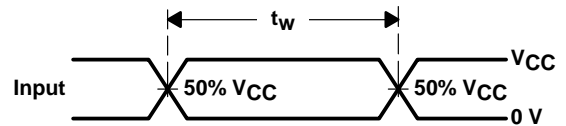
PARAMETER MEASUREMENT INFORMATION



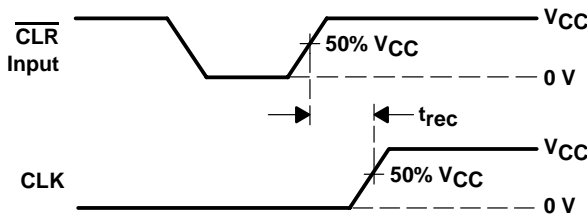
† When  $V_{CC} = 1.5\text{ V}$ ,  $R_1 = R_2 = 1\text{ k}\Omega$

LOAD CIRCUIT

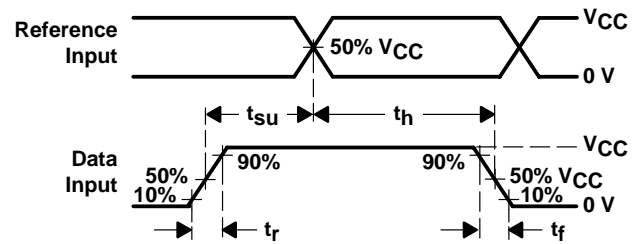
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND



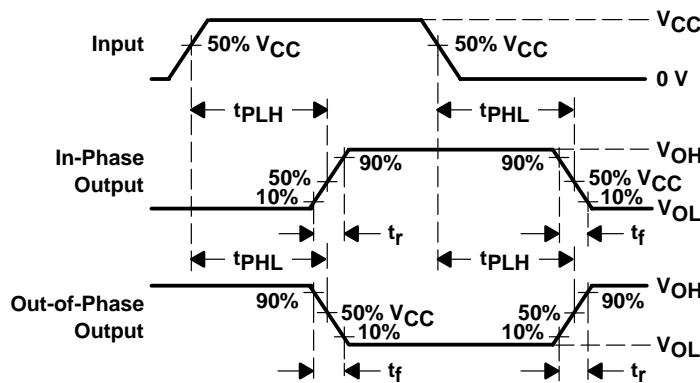
VOLTAGE WAVEFORMS  
 PULSE DURATION



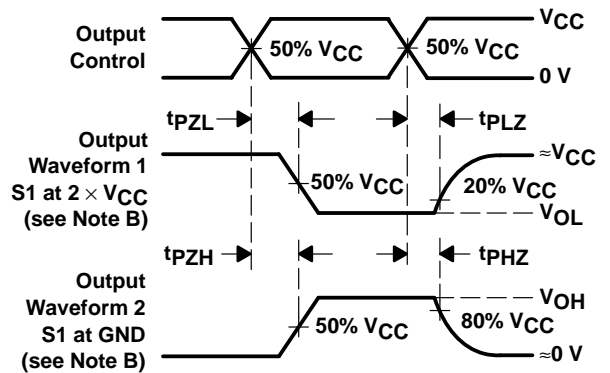
VOLTAGE WAVEFORMS  
 RECOVERY TIME



VOLTAGE WAVEFORMS  
 SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS  
 PROPAGATION DELAY AND OUTPUT TRANSITION TIMES



VOLTAGE WAVEFORMS  
 OUTPUT ENABLE AND DISABLE TIMES

- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r = 3\text{ ns}$ ,  $t_f = 3\text{ ns}$ . Phase relationships between waveforms are arbitrary.  
 D. For clock inputs,  $f_{max}$  is measured with the input duty cycle at 50%.  
 E. The outputs are measured one at a time with one input transition per measurement.  
 F.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 G.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 H.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CD54AC02F3A	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD54AC02F3A	<a href="#">Samples</a>
CD74AC02E	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC02E	<a href="#">Samples</a>
CD74AC02EE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD74AC02E	<a href="#">Samples</a>
CD74AC02M	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC02M	<a href="#">Samples</a>
CD74AC02M96	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC02M	<a href="#">Samples</a>
CD74AC02M96E4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC02M	<a href="#">Samples</a>
CD74AC02M96G4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC02M	<a href="#">Samples</a>
CD74AC02ME4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC02M	<a href="#">Samples</a>
CD74AC02MG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	AC02M	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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**OTHER QUALIFIED VERSIONS OF CD54AC02, CD74AC02 :**

- Catalog: [CD74AC02](#)
- Military: [CD54AC02](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74AC02M96	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



**TAPE AND REEL BOX DIMENSIONS**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74AC02M96	SOIC	D	14	2500	367.0	367.0	38.0

J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

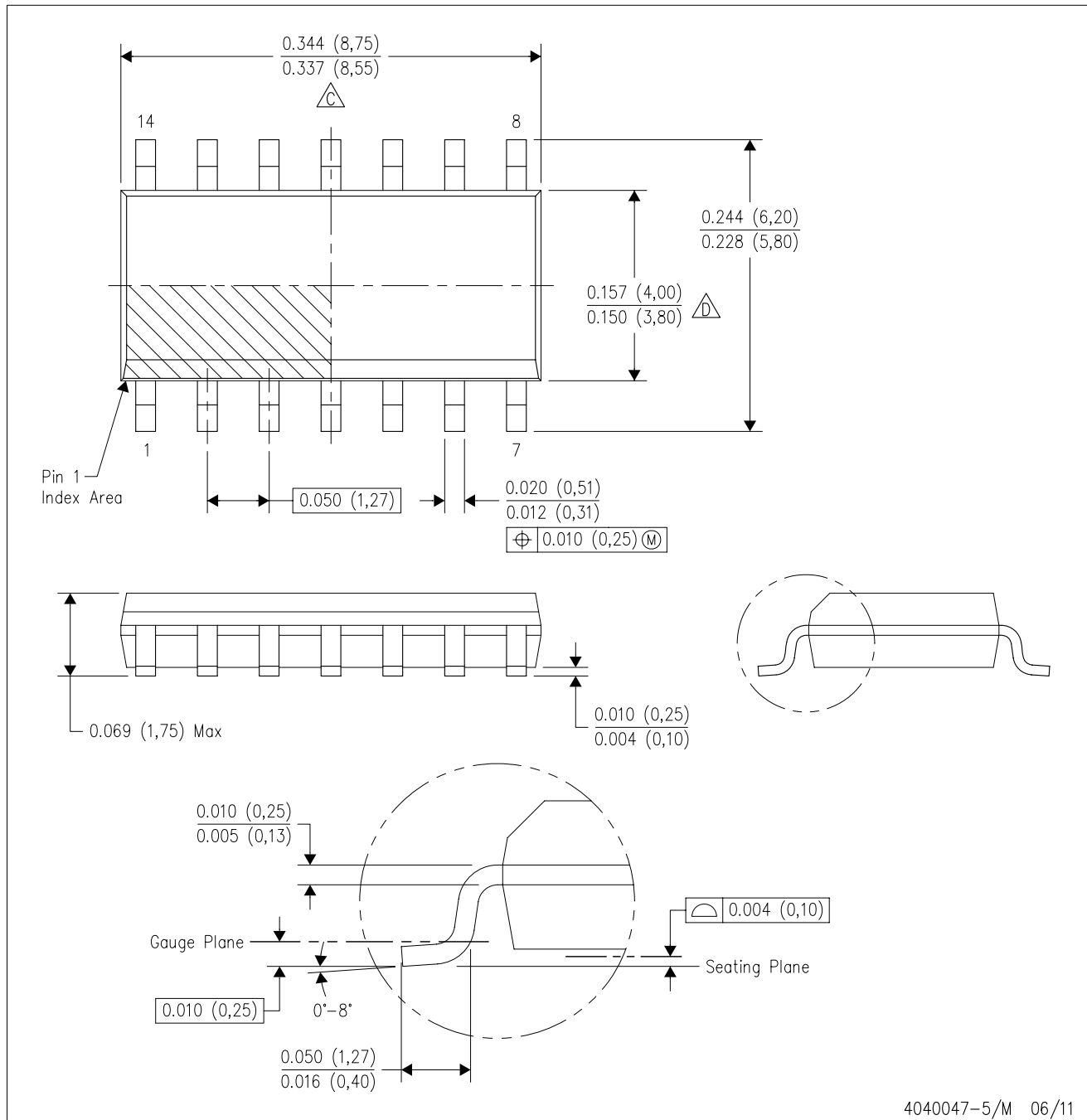


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - $\triangle D$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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### Applications

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Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
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